

Part Number:  
KH-3030175-Y1

 Checker/Date  
Henry  
06/01/18'

 Inspector/Date  
Henry  
06/01/18'

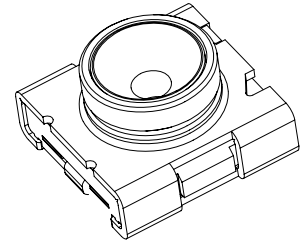
 Maker/Date  
SAM  
06/01/18'

### 1、Overview

This product is applied to RF circuits and provides a switch interface for circuit tests, And it's the first type of the "MINI RF CONNECTOR".

### 2、Technology Parameters

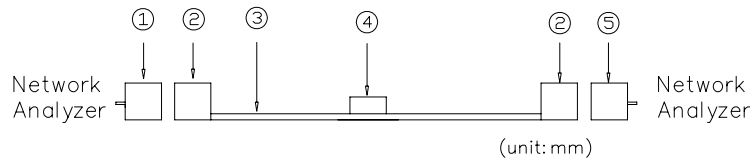
2.1 Rated Voltage	250V AC
2.2 Frequency Range	0~6GHz
2.3 Impedance	50Ω
2.4 Operating Temperature	-40°C ~ +85°C



### 3、Electrical Performance

3.1 Insulation Resistance	500MΩ
3.2 Dielectric Withstanding Voltage	300V AC
3.3 Contact Resistance	120 mΩ max
3.4 Voltage Standing Wave Ratio(VSWR)	1.2 max (DC~3GHz), 1.3 max (3~6GHz)

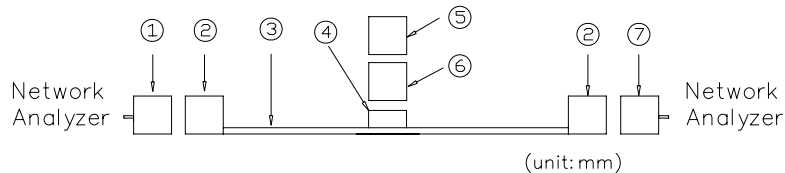
#### 3.4.1 Test Methods:



- |                   |             |
|-------------------|-------------|
| ① Port 1          | ④ 818000251 |
| ② SMA Jack        | ⑤ Port 2    |
| ③ Microstrip line |             |

3.5 Isolation 20dBmin (DC~3GHz), 15dBmin (3~6GHz)

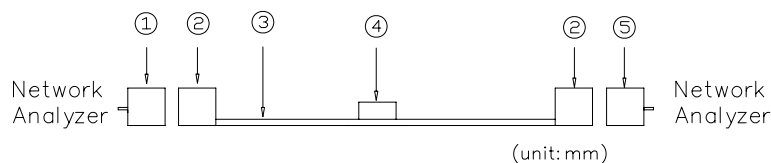
#### 3.5.1 Test Methods:



- |                   |                                   |
|-------------------|-----------------------------------|
| ① Port 1          | ④ 818000251                       |
| ② SMA Jack        | ⑤ Termination                     |
| ③ Microstrip line | ⑥ Probe for automatic measurement |
|                   | ⑦ Port 2                          |

3.6 Insertion loss 0.10dBmax (DC~3GHz), 0.20dBmax (3~6GHz)

#### 3.6.1 Test Methods:



- |                   |             |
|-------------------|-------------|
| ① Port 1          | ④ 818000251 |
| ② SMA Jack        | ⑤ Port 2    |
| ③ Microstrip line |             |



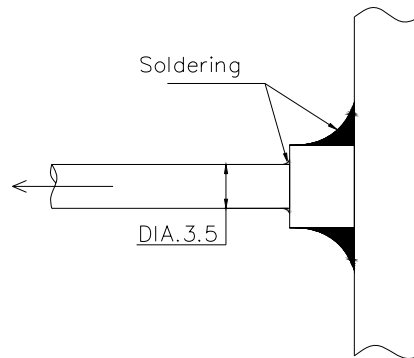
**Product Specification**

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Part Number:	KH-3030175-Y1	Checker/Date	Inspector/Date	Maker/Date	
		Henry 06/01/18'	Henry 06/01/18'	SAM 06/01/18'	

**4 Mechanical Performance**

- 4.1 Contact Stress 3.4N~4.5N
- 4.2 Mating Force 30N max
- 4.3 Unmating Force 5N~40N
- 4.4 Durability 500 cycles
- 4.5 Adhered Force of Solders 50N

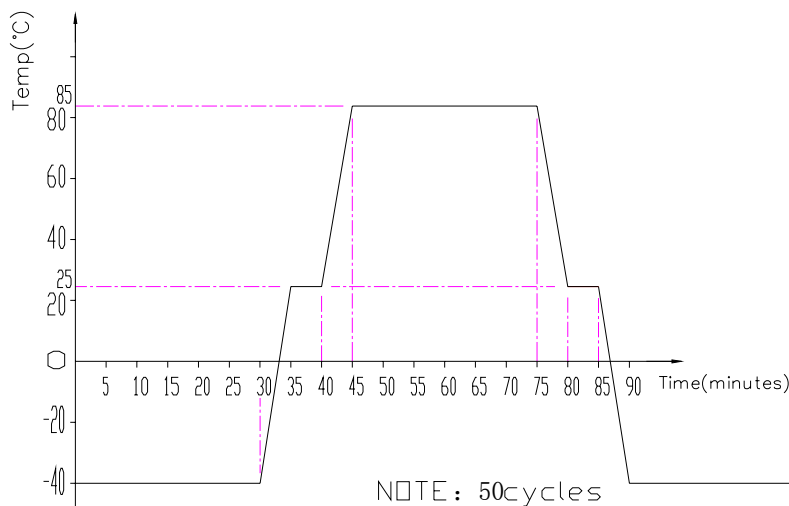
**4.5.1 Test Methods:**



- 4.6 Shock Acceleration: 750m/s<sup>2</sup> (Peak);  
Duration of Shock: 6m sec.  
Wave form: Half-sine
- 4.7 Vibration 10Hz~30Hz : 3mm

**5 Environment Performance**

**5.1 Thermal Shock**

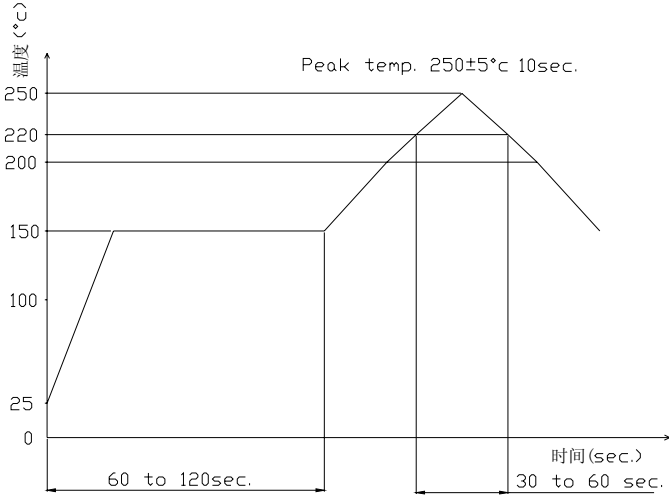


**5.2 Static Humidity & Thermal Test**

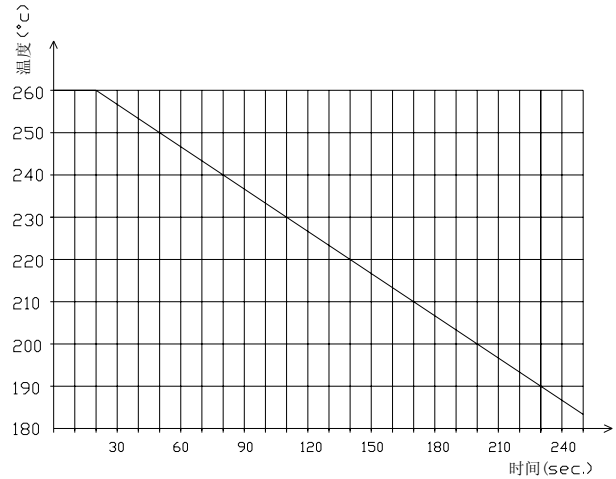
- Temperature: 60°C
- Humidity: 95% RH
- Time: 96 hours

### 6、SMT Temperature Curve

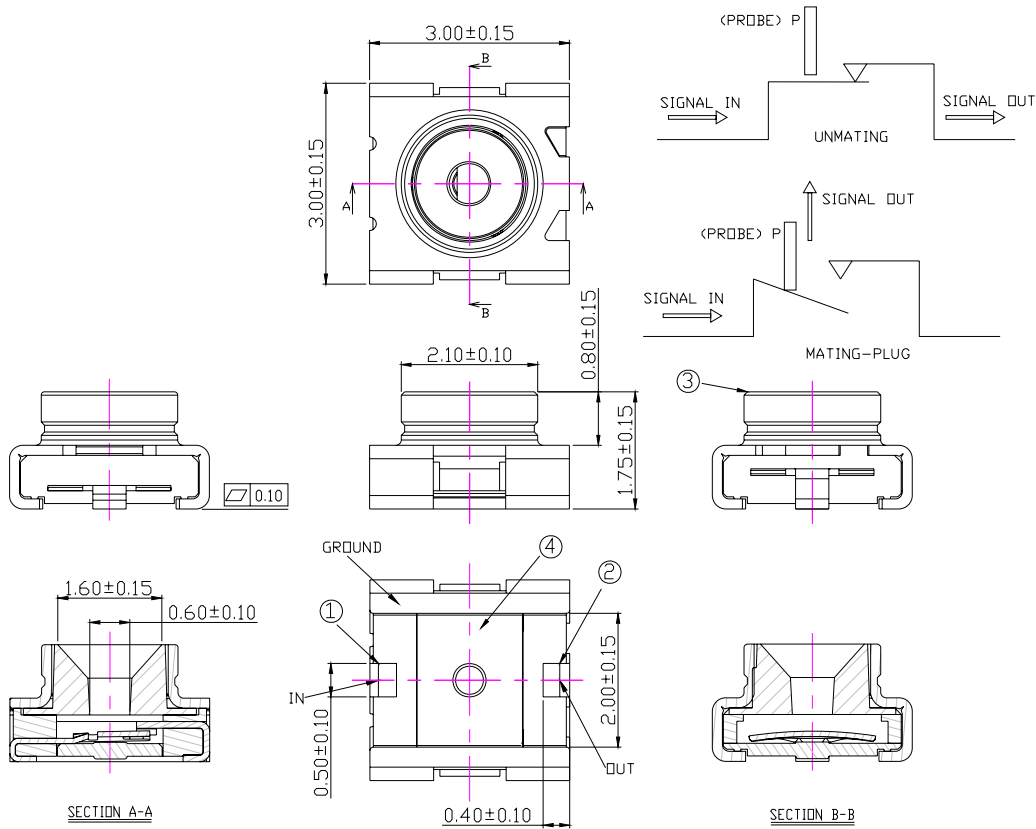
#### 6.1 Reflow Soldering Standard Conditions



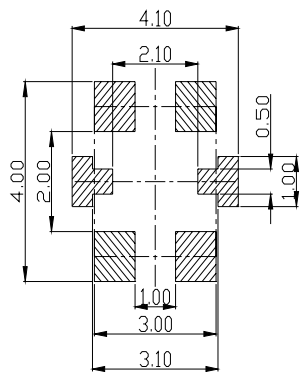
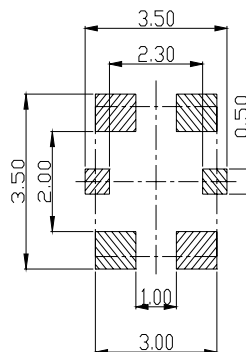
#### 6.2 Allowable Temperature and Time of Reflow Soldering



### 7、Appearance Dimension

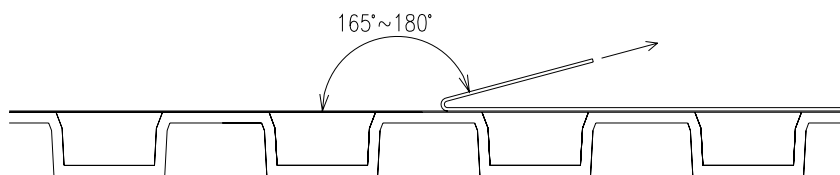
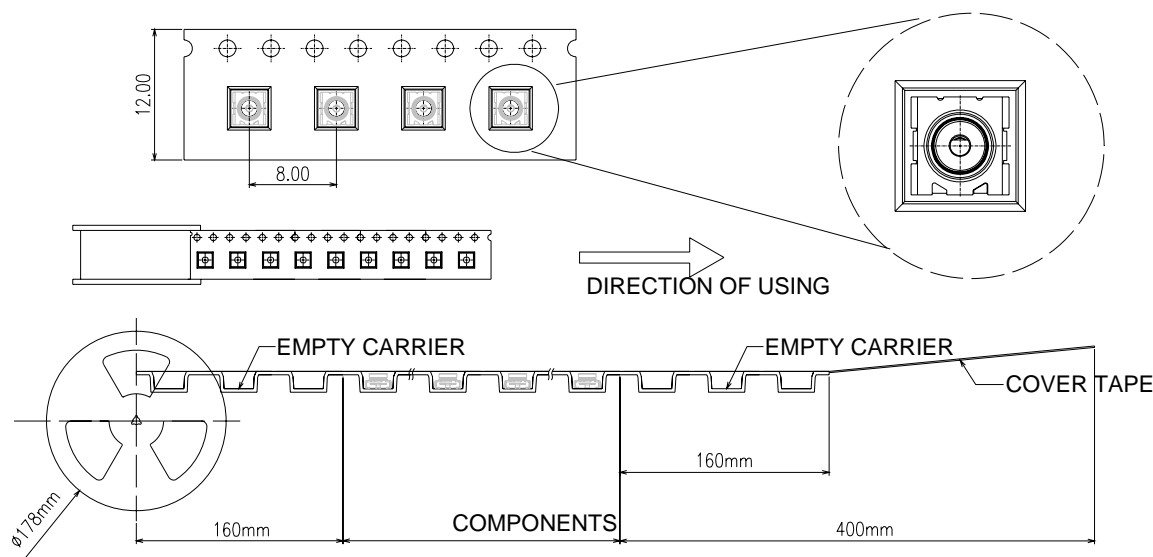


4	Case	Engineering plastic	UL 94V-0, BLACK	1
3	Output terminal	Copper Alloy	50u"Ni Overall, Contact Area Au2u", Soldering Area Gold Flash	1
2	Input terminal(R)	Copper Alloy	50u"Ni Overall, Contact Area Au5u", Soldering Area Gold Flash	1
1	Input terminal(C)	Stainless Steel	50u"Ni Overall, Contact Area Au5u", Soldering Area Gold Flash	1
No.	Part Name	Material	Finish	Q'ty

**8、Printed circuit board (PCB) pad**

 Recommend PCB Layout  
General Tolerance:  $\pm 0.05$ 

 The standard solder stencil mask pattern  
(Mask thickness 0.15mm)

**9、PACKING SPECIFICATION**
**9.1 Peeling off Force of Cover Tape**

When cover tape is peeled off as in right figure by a speed of 300mm/minute. The peeling off force should be 1.3N maximum.


**9.2 THE WAY OF PACKAGE : TAPE PACKING, 1000Pcs/REEL (Φ178mm)**

**10、Storage Conditions**

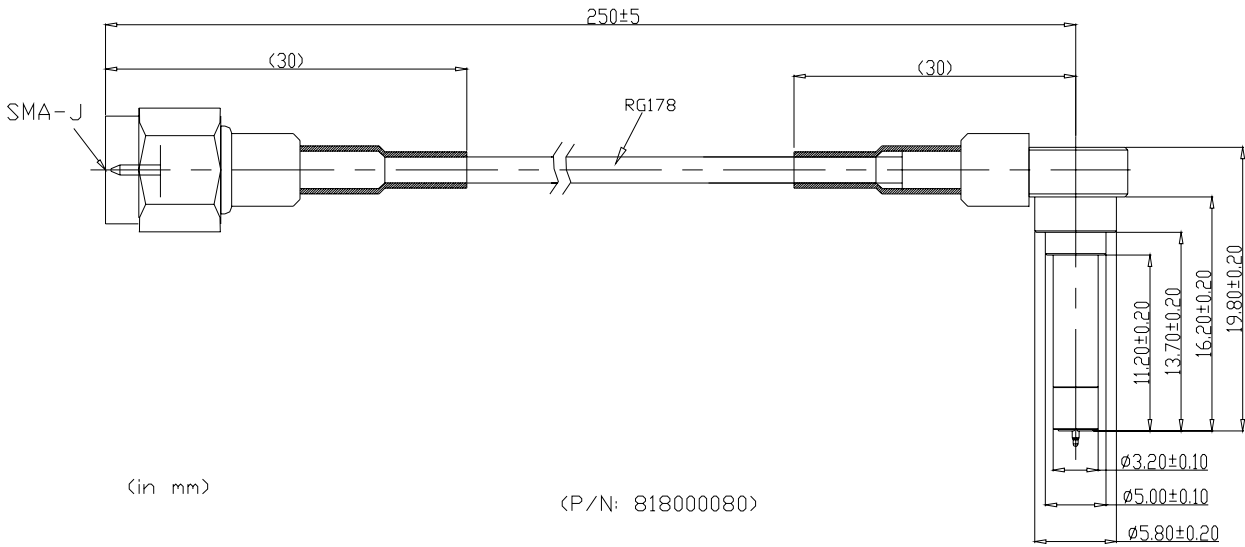
 Temperature:  $-10 \sim +40$  °C

Moisture: 15~85 % RH

Valid Period: 6 months

11、Accessories for Tests

TYPE I :



TYPE II :

